

## Overview

KEMET's Space Grade Series of capacitors are suitable for use by defense/aerospace customers in high reliability space applications. This series meets the requirements of MIL-PRF-55365 as well as MIL-STD-1580. These capacitors incorporate an intensive testing and screening protocol which is customizable depending on specific customer requirements. The full part number allows for designation of Weibull grading

level (C=0.01%/k hours), surge current level (10 cycles -55°C and +85°C before and/or after Weibull grading), performance testing level (see chart for details on available options), ESR (low and standard), and termination finish (see description in each series). Fused versions are available for built-in circuit protection, as well as multi-anode designs for very low ESR values.

## Benefits

- ESR as low as 18 mΩ
- High ripple current capability
- RoHS Compliant and lead-free terminations
- 100% steady-state accelerated aging
- 100% surge current test
- Meets or exceeds EIA standard 535BAAC
- Taped and reeled per EIA 481-1
- Weibull Grading C (0.01%/1,000 hours)
- Operating temperature range of -55°C to +125°C

## Applications

Typical applications include decoupling and filtering in defense and aerospace end applications, such as DC/DC converters, portable electronics, telecommunications, and control units requiring high ripple current capability.



## Environmental Compliance

RoHS Compliant (6/6) according to Directive 2002/95/EC when ordered with 100% Sn solder.



RoHS Compliant

## SPICE

For a detailed analysis of specific part numbers, please visit [www.kemet.com](http://www.kemet.com) for a free download of KEMET's SPICE software. The KEMET SPICE program is freeware intended to aid design engineers in analyzing the performance of these capacitors over frequency, temperature, ripple, and DC bias conditions.

## Ordering Information

T	510	X	477	M	006	C	T	61	1	A
Capacitor Class	Series	Case Size	Capacitance Code (pF)	Capacitance Tolerance	Voltage	Failure Rate/ Design	Lead Material	Surge	ESR	Testing
T = Tantalum	Ultra Low ESR - Space Grade	E, X	First two digits represent significant figures. Third digit specifies number of zeros.	K = ±10% M = ±20%	004 = 4 V 006 = 6.3 V 010 = 10 V	C = 0.01%/1,000 hours	C = Hot Solder Dipped T = 100% Matte Tin (Sn) Plated H = Standard Solder Coated (SnPb 5% Pb minimum)	61 = None 62 = 10 Cycles 25°C 63 = 10 Cycles, -55°C and 85°C before Weibull 64 = 10 Cycles, -55°C and 85°C after Weibull 65 = Both	1 = ESR - Standard	A = Option A B = Option B C = Option C

## Performance Characteristics

Item	Performance Characteristics
Operating Temperature	-55°C to 125°C
Rated Capacitance Range	10 – 1,000 µF @ 120 Hz/25°C
Capacitance Tolerance	K Tolerance (10%), M Tolerance (20%)
Rated Voltage Range	4 – 10 V
DF (120 Hz)	Refer to Part Number Electrical Specification Table
ESR (100 kHz)	Refer to Part Number Electrical Specification Table
Leakage Current	≤ 0.01 CV (µA) at rated voltage after 5 minutes

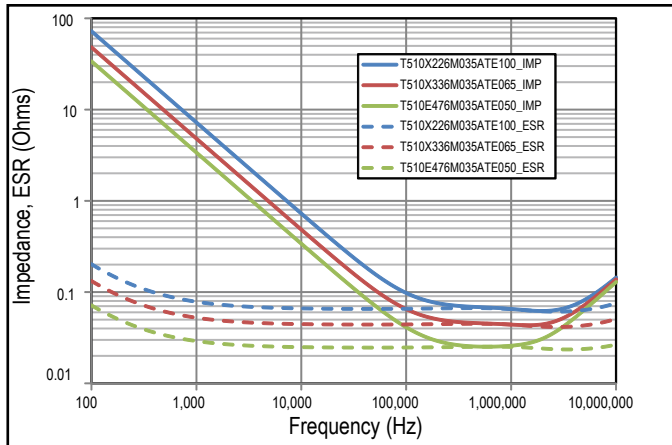
## Qualification

Test	Condition	Characteristics				
Endurance	85°C @ rated voltage, 2,000 hours 125°C @ 2/3 rated voltage, 2,000 hours	Δ C/C	Within ±10% of initial value			
		DF	Within initial limits			
		DCL	Within 1.25 x initial limit			
		ESR	Within initial limits			
Storage Life	125°C @ 0 volts, 2,000 hours	Δ C/C	Within ±10% of initial value			
		DF	Within initial limits			
		DCL	Within 1.25 x initial limit			
		ESR	Within initial limits			
Thermal Shock	MIL-STD-202, Method 107, Condition B, mounted, -55°C to 125°C, 1,000 cycles	Δ C/C	Within ±5% of initial value			
		DF	Within initial limits			
		DCL	Within 1.25 x initial limit			
		ESR	Within initial limits			
Temperature Stability	Extreme temperature exposure at a succession of continuous steps at +25°C, -55°C, +25°C, +85°C, +125°C, +25°C	Δ C/C	+25°C	-55°C	+85°C	+125°C
		DF	IL*	±10%	±10%	±20%
		DCL	IL	IL	1.5 x IL	1.5 x IL
Surge Voltage	25°C and 85°C, 1.32 x rated voltage 1,000 cycles. (125°C, 1.2 x rated voltage)	Δ C/C	Within ±5% of initial value			
		DF	Within initial limits			
		DCL	Within initial limits			
		ESR	Within initial limits			
Mechanical Shock/Vibration	MIL-STD-202, Method 213, Condition I, 100 G peak. MIL-STD-202, Method 204, Condition D, 10 Hz to 2,000 Hz, 20 G peak	Δ C/C	Within ±10% of initial value			
		DF	Within initial limits			
		DCL	Within initial limits			

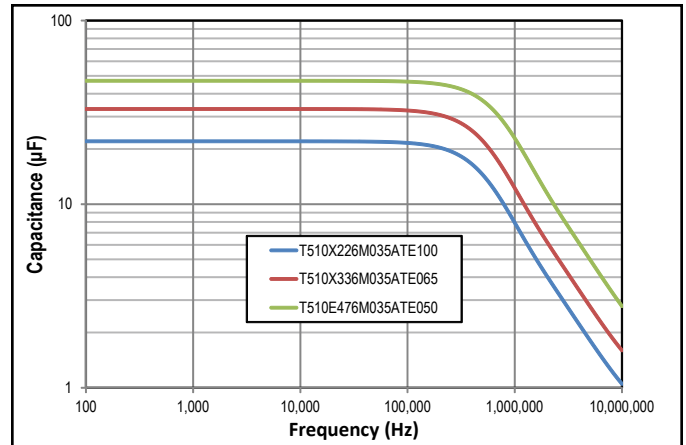
\*IL = Initial limit

## Electrical Characteristics

Impedance, ESR vs. Frequency

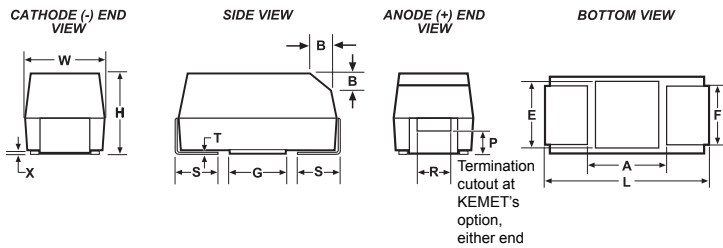


Capacitance vs. Frequency



## Dimensions – Millimeters (Inches)

Metric will govern



Case Size		Component													
KEMET	EIA	L*	W*	H*	F* ±0.1 ±(.004)	S* ±0.3 ±(.012)	B* ±0.15 (Ref) ±.006	X (Ref)	P (Ref)	R (Ref)	T (Ref)	A (Min)	G (Ref)	E (Ref)	
X	7343-43	7.3 ±0.3 (0.287 ±0.012)	4.3 ±0.3 (0.169 ±0.012)	4.0 ±0.3 (0.157 ±0.012)	2.4 (.094)	1.3 (.051)	0.5 (.020)	0.10 ± 0.10 (.004 ± .004)	1.7 (.067)	1.0 (.039)	0.13 (.005)	3.8 (.150)	3.5 (.138)	3.5 (.138)	
E	7360-38	7.3 ±0.3 (0.287 ±0.012)	6.0 ±0.3 (0.236 ±0.012)	3.6 ±0.2 (0.142 ±0.008)	4.1 (.161)	1.3 (.051)	0.5 (.020)	0.10 ± 0.10 (.004 ± .004)	n/a	n/a	0.13 (.005)	3.8 (.150)	3.5 (.138)	3.5 (.138)	

Notes: (Ref) – Dimensions provided for reference only. No dimensions are provided for B, P or R because low profile cases do not have a bevel or a notch.

\* MIL-C-55365/8 specified dimensions

**Table 1 – Ratings & Part Number Reference**

Rated Voltage	Rated Cap	Case Code/ Case Size	KEMET Part Number	DC Leakage	DF	ESR	Maximum Allowable Ripple Current			Moisture Sensitivity
							(mA) 100 kHz +25°C	(mA) 100 kHz +85°C	(mA) 100 kHz +125°C	
V	μF	KEMET/EIA	(See below for part options)	μA @ +20°C Maximum/5 Min	% @ +20°C 120 Hz Maximum	Ω @ +20°C 100 kHz Maximum				Temperature ≤ 260°C
4	1000	X/7343-43	T510X108(1)004C(2)(3)1(4)	40	6	18	3.9	3.5	1.5	1
6.3	680	E/7360-38	T510E687(1)006C(2)(3)1(4)	40.8	6	23	3.5	3.2	1.4	1
10	330	X/7343-43	T510X337(1)010C(2)(3)1(4)	33	6	35	2.8	2.5	1.1	1

(1) To complete KEMET part number, insert M for ±20%, K for ±10%. Designates Capacitance tolerance.

(2) To complete KEMET part number, insert C (0.01%/1,000 hours). Designates Reliability Level.

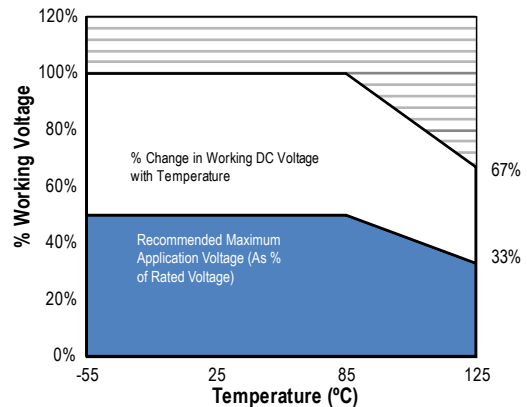
(3) To complete KEMET part number, insert H = Solder Plated or T = 100% Tin (Sn). Designates Termination Finish.

(4) To complete KEMET part number, insert 61 = None, 62 = 10 cycles +25°C, 63 = 10 cycles -55°C +85°C after Weibull, 64 = 10 cycles -55°C +85°C before Weibull or 65 = Both. Designates Surge current option.

(Refer to Ordering Information for additional detail.)

## Recommended Voltage Derating Guidelines

	-55°C to 85°C	85°C to 125°C
% Change in Working DC Voltage with Temperature	V <sub>R</sub>	67% of V <sub>R</sub>
Recommended Maximum Application Voltage	50% of V <sub>R</sub>	33% of V <sub>R</sub>



## Ripple Current/Ripple Voltage

Permissible AC ripple voltage and current are related to equivalent series resistance (ESR) and the power dissipation capabilities of the device. Permissible AC ripple voltage which may be applied is limited by two criteria:

1. The positive peak AC voltage plus the DC bias voltage, if any, must not exceed the DC voltage rating of the capacitor.
2. The negative peak AC voltage in combination with bias voltage, if any, must not exceed the allowable limits specified for reverse voltage. See the Reverse Voltage section for allowable limits.

The maximum power dissipation by case size can be determined using the table at right. The maximum power dissipation rating stated in the table must be reduced with increasing environmental operating temperatures. Refer to the table below for temperature compensation requirements.

KEMET Series and Case Code	EIA Case Code	Maximum Power Dissipation (P max) mWatts @ 25°C w/+20°C Rise
T510X	7343-43	270
T510E	7360-38	285

The maximum power dissipation rating must be reduced with increasing environmental operating temperatures. Refer to the Temperature Compensation Multiplier table for details.

Temperature Compensation Multipliers for Maximum Power Dissipation		
T ≤ 25°C	T ≤ 85°C	T ≤ 125°C
1.00	0.90	0.40

T = Environmental Temperature

Using the P max of the device, the maximum allowable rms ripple current or voltage may be determined.

$$I(max) = \sqrt{P_{max}/R}$$

$$E(max) = Z \sqrt{P_{max}/R}$$

I = rms ripple current (amperes)

E = rms ripple voltage (volts)

P max = maximum power dissipation (watts)

R = ESR at specified frequency (ohms)

Z = Impedance at specified frequency (ohms)

## Reverse Voltage

Solid tantalum capacitors are polar devices and may be permanently damaged or destroyed if connected with the wrong polarity. The positive terminal is identified on the capacitor body by a stripe plus in some cases a beveled edge. A small degree of transient reverse voltage is permissible for short periods per the table. The capacitors should not be operated continuously in reverse mode, even within these limits.

Temperature	Permissible Transient Reverse Voltage
25°C	15% of Rated Voltage
85°C	5% of Rated Voltage
125°C	1% of Rated Voltage

### Table 2 – Land Dimensions/Courtyard

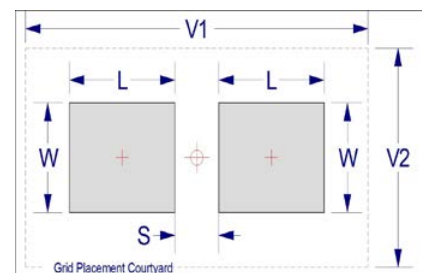
KEMET	Metric Size Code	Density Level A: Maximum (Most) Land Protrusion (mm)					Density Level B: Median (Nominal) Land Protrusion (mm)					Density Level C: Minimum (Least) Land Protrusion (mm)					
		Case	EIA	W	L	S	V1	V2	W	L	S	V1	V2	W	L	S	V1
E <sup>1</sup>	7360-38		4.25	2.77	3.67	10.22	7.30	4.13	2.37	3.87	9.12	6.80	4.03	1.99	4.03	8.26	6.54
X <sup>1</sup>	7343-43		2.55	2.77	3.67	10.22	5.60	2.43	2.37	3.87	9.12	5.10	2.33	1.99	4.03	8.26	4.84

**Density Level A:** For low-density product applications. Recommended for wave solder applications and provides a wider process window for reflow solder processes.

**Density Level B:** For products with a moderate level of component density. Provides a robust solder attachment condition for reflow solder processes.

**Density Level C:** For high component density product applications. Before adapting the minimum land pattern variations the user should perform qualification testing based on the conditions outlined in IPC Standard 7351 (IPC-7351).

<sup>1</sup> Height of these chips may create problems in wave soldering.



## Soldering Process

KEMET's families of surface mount capacitors are compatible with wave (single or dual), convection, IR, or vapor phase reflow techniques. Preheating of these components is recommended to avoid extreme thermal stress. KEMET's recommended profile conditions for convection and IR reflow reflect the profile conditions of the IPC/J-STD-020D standard for moisture sensitivity testing. The devices can safely withstand a maximum of three reflow passes at these conditions.

Please note that although the X/7343-43 case size can withstand wave soldering, the tall profile (4.3 mm maximum) dictates care in wave process development.

Hand soldering should be performed with care due to the difficulty in process control. If performed, care should be taken to avoid contact of the soldering iron to the molded case. The iron should be used to heat the solder pad, applying solder between the pad and the termination, until reflow occurs. Once reflow occurs, the iron should be removed immediately. "Wiping" the edges of a chip and heating the top surface is not recommended.

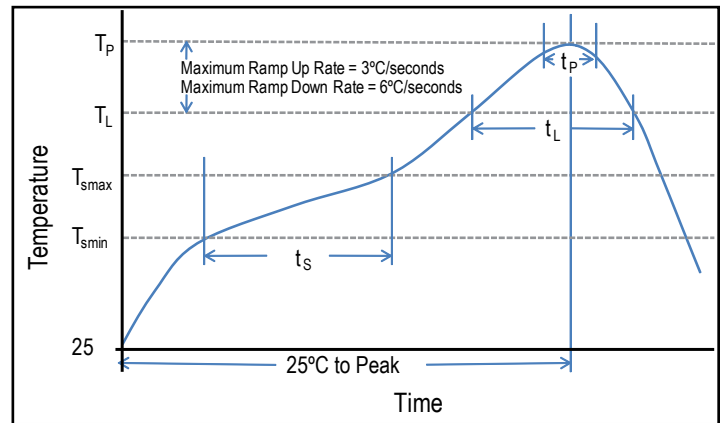
During typical reflow operations, a slight darkening of the gold-colored epoxy may be observed. This slight darkening is normal and not harmful to the product. Marking permanency is not affected by this change.

Profile Feature	SnPb Assembly	Pb-Free Assembly
<b>Preheat/Soak</b>		
Temperature Minimum ( $T_{smin}$ )	100°C	150°C
Temperature Maximum ( $T_{smax}$ )	150°C	200°C
Time ( $t_s$ ) from $T_{smin}$ to $T_{smax}$	60 – 120 seconds	60 – 120 seconds
Ramp-up Rate ( $T_L$ to $T_p$ )	3°C/seconds maximum	3°C/seconds maximum
Liquidous Temperature ( $T_L$ )	183°C	217°C
Time Above Liquidous ( $t_L$ )	60 – 150 seconds	60 – 150 seconds
Peak Temperature ( $T_p$ )	220°C* 235°C**	250°C* 260°C**
Time within 5°C of Maximum Peak Temperature ( $t_p$ )	20 seconds maximum	30 seconds maximum
Ramp-down Rate ( $T_p$ to $T_L$ )	6°C/seconds maximum	6°C/seconds maximum
Time 25°C to Peak	6 minutes maximum	8 minutes maximum

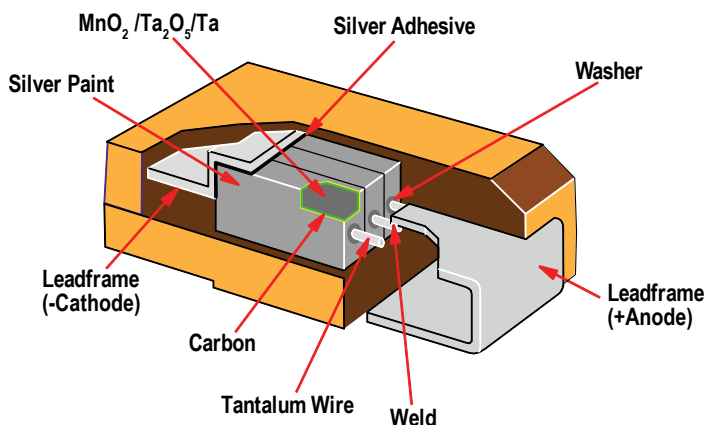
Note: All temperatures refer to the center of the package, measured on the package body surface that is facing up during assembly reflow.

\*Case Size D, E, P, Y, and X

\*\*Case Size A, B, C, H, I, K, M, R, S, T, U, V, W, and Z

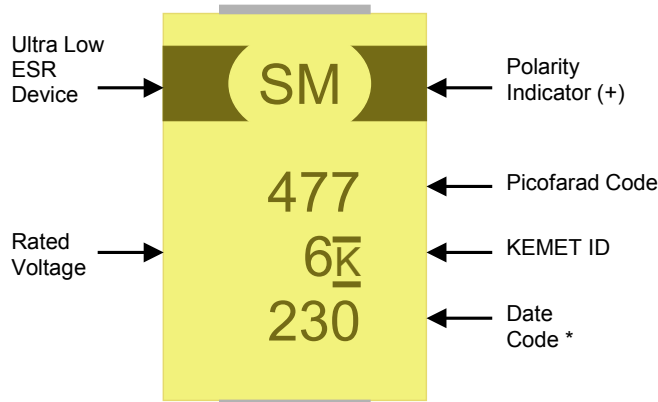


## Construction





## Capacitor Marking



\* 230 = 30<sup>th</sup> week of 2012

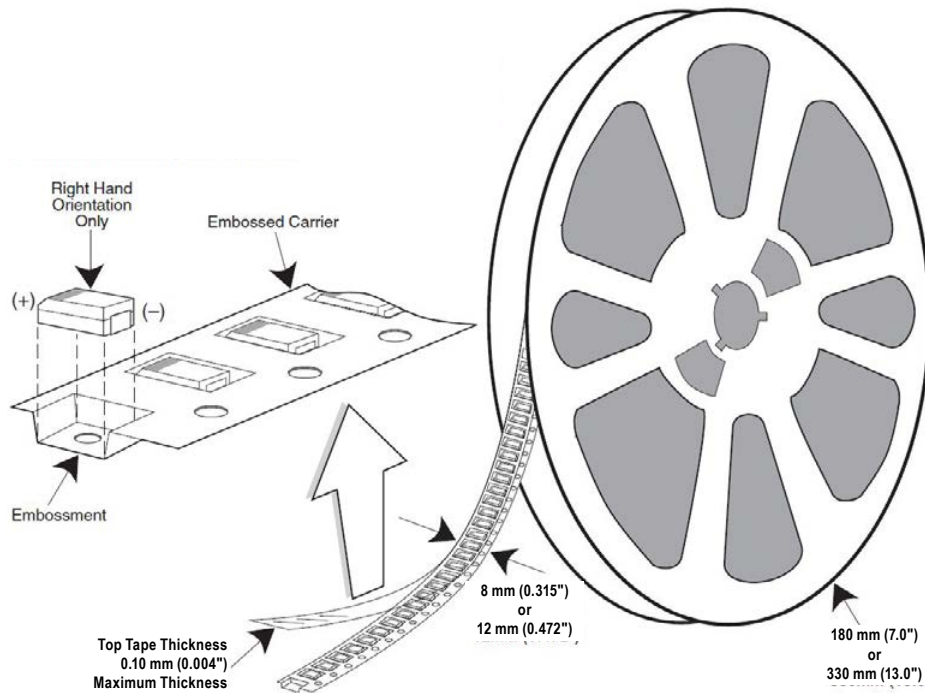
Date Code *	
1 <sup>st</sup> digit = Last number of Year	9 = 2009 0 = 2010 1 = 2011 2 = 2012 3 = 2013 4 = 2014
2 <sup>nd</sup> and 3 <sup>rd</sup> digit = Week of the Year	01 = 1 <sup>st</sup> week of the Year to 52 = 52 <sup>nd</sup> week of the Year

## Storage

Tantalum chip capacitors should be stored in normal working environments. While the chips themselves are quite robust in other environments, solderability will be degraded by exposure to high temperatures, high humidity, corrosive atmospheres, and long term storage. In addition, packaging materials will be degraded by high temperature— reels may soften or warp and tape peel force may increase. KEMET recommends that maximum storage temperature not exceed 40°C and maximum storage humidity not exceed 60% relative humidity. Temperature fluctuations should be minimized to avoid condensation on the parts and atmospheres should be free of chlorine and sulphur bearing compounds. For optimized solderability chip stock should be used promptly, preferably within three years of receipt.

## Tape & Reel Packaging Information

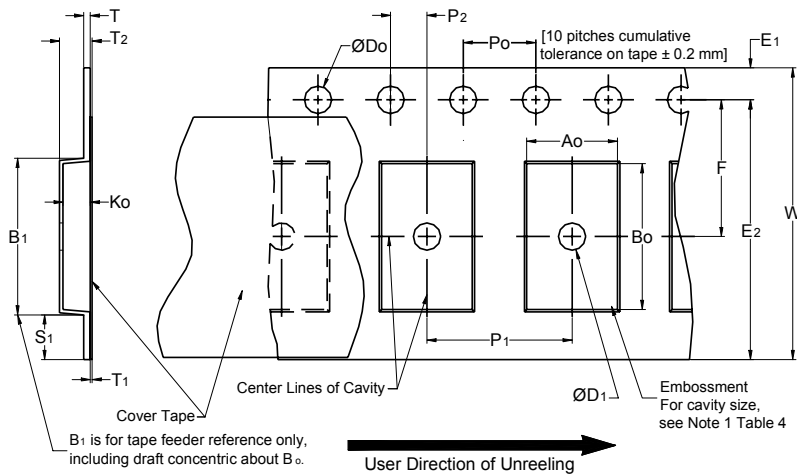
KEMET's molded tantalum and aluminum chip capacitor families are packaged in 8 and 12 mm plastic tape on 7" and 13" reels in accordance with *EIA Standard 481-1: Embossed Carrier Taping of Surface Mount Components for Automatic Handling*. This packaging system is compatible with all tape-fed automatic pick-and-place systems.



**Table 3 – Packaging Quantity**

Case Code		Tape Width (mm)	7" Reel*
KEMET	EIA		
X	7343-43	12	500
E	7360-38	12	500

**Figure 1 – Embossed (Plastic) Carrier Tape Dimensions**



**Table 4 – Embossed (Plastic) Carrier Tape Dimensions**

Metric will govern

Constant Dimensions — Millimeters (Inches)									
Tape Size	D <sub>0</sub>	D <sub>1</sub> Minimum Note 1	E <sub>1</sub>	P <sub>0</sub>	P <sub>2</sub>	R Reference Note 2	S <sub>1</sub> Minimum Note 3	T Maximum	T <sub>1</sub> Maximum
8 mm	1.5 +0.10/-0.0 (0.059 +0.004/-0.0)	1.0 (0.039)	1.75 ±0.10 (0.069 ±0.004)	4.0 ±0.10 (0.157 ±0.004)	2.0 ±0.05 (0.079 ±0.002)	25.0 (0.984)	0.600 (0.024)	0.600 (0.024)	0.100 (0.004)
12 mm		1.5 (0.059)				30 (1.181)			
16 mm									
Variable Dimensions — Millimeters (Inches)									
Tape Size	Pitch	B <sub>1</sub> Maximum Note 4	E <sub>2</sub> Minimum	F	P <sub>1</sub>	T <sub>2</sub> Maximum	W Maximum	A <sub>0</sub> , B <sub>0</sub> & K <sub>0</sub>	
8 mm	Single (4 mm)	4.35 (0.171)	6.25 (0.246)	3.5 ±0.05 (0.138 ±0.002)	4.0 ±0.10 (0.157 ±0.004)	2.5 (0.098)	8.3 (0.327)	Note 5	
12 mm	Single (4 mm) & Double (8 mm)	8.2 (0.323)	10.25 (0.404)	5.5 ±0.05 (0.217 ±0.002)	8.0 ±0.10 (0.315 ±0.004)	4.6 (0.181)	12.3 (0.484)		
16 mm	Triple (12 mm)	12.1 (0.476)	14.25 (0.561)	5.5 ±0.05 (0.217 ±0.002)	8.0 ±0.10 (0.315 ±0.004)	4.6 (0.181)	16.3 (0.642)		

- The embossment hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of embossment location and hole location shall be applied independent of each other.
- The tape, with or without components, shall pass around R without damage (see Figure 5).
- If S<sub>1</sub> < 1.0 mm, there may not be enough area for cover tape to be properly applied (see EIA Standard 481–D, paragraph 4.3, section b).
- B<sub>1</sub> dimension is a reference dimension for tape feeder clearance only.
- The cavity defined by A<sub>0</sub>, B<sub>0</sub> and K<sub>0</sub> shall surround the component with sufficient clearance that:
  - the component does not protrude above the top surface of the carrier tape.
  - the component can be removed from the cavity in a vertical direction without mechanical restriction, after the top cover tape has been removed.
  - rotation of the component is limited to 20° maximum for 8 and 12 mm tapes and 10° maximum for 16 mm tapes (see Figure 2).
  - lateral movement of the component is restricted to 0.5 mm maximum for 8 mm and 12 mm wide tape and to 1.0 mm maximum for 16 mm tape (see Figure 3).
  - see Addendum in EIA Standard 481–D for standards relating to more precise taping requirements.

## Packaging Information Performance Notes

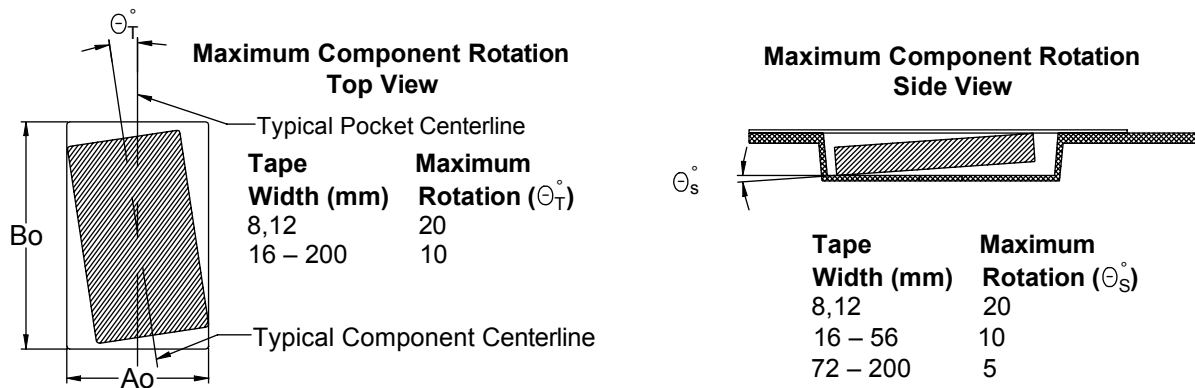
- Cover Tape Break Force:** 1.0 Kg minimum.
- Cover Tape Peel Strength:** The total peel strength of the cover tape from the carrier tape shall be:

Tape Width	Peel Strength
8 mm	0.1 to 1.0 Newton (10 to 100 gf)
12 and 16 mm	0.1 to 1.3 Newton (10 to 130 gf)

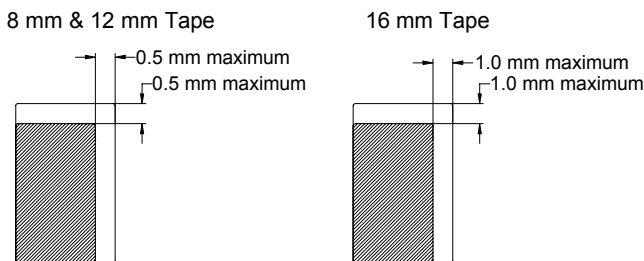
The direction of the pull shall be opposite the direction of the carrier tape travel. The pull angle of the carrier tape shall be 165° to 180° from the plane of the carrier tape. During peeling, the carrier and/or cover tape shall be pulled at a velocity of 300 ±10 mm/minute.

- Labeling:** Bar code labeling (standard or custom) shall be on the side of the reel opposite the sprocket holes. Refer to EIA Standards 556 and 624.

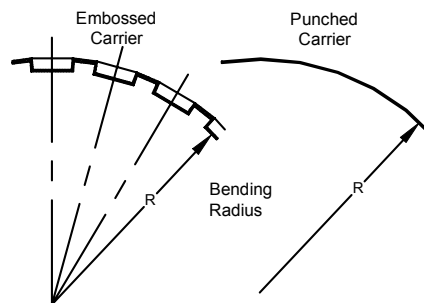
**Figure 2 – Maximum Component Rotation**



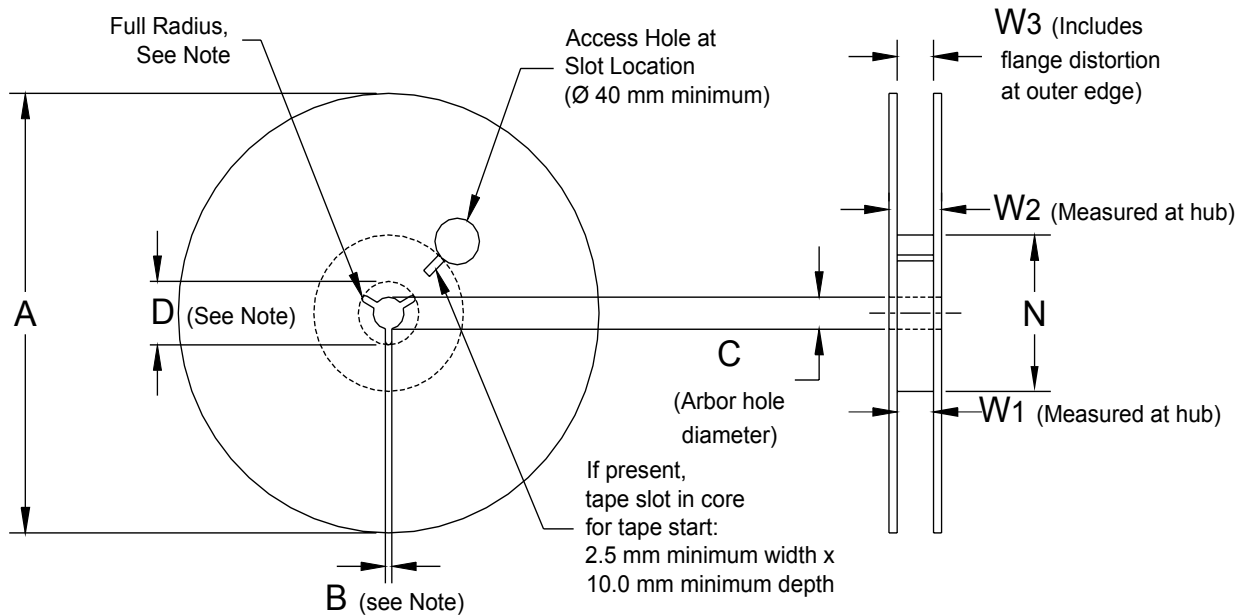
**Figure 3 – Maximum Lateral Movement**



**Figure 4 – Bending Radius**



### Figure 5 – Reel Dimensions



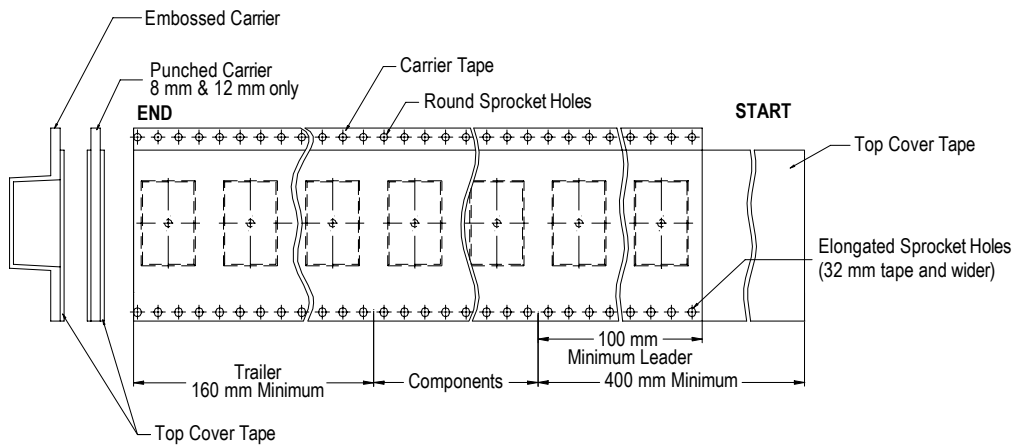
Note: Drive spokes optional; if used, dimensions B and D shall apply.

### Table 5 – Reel Dimensions

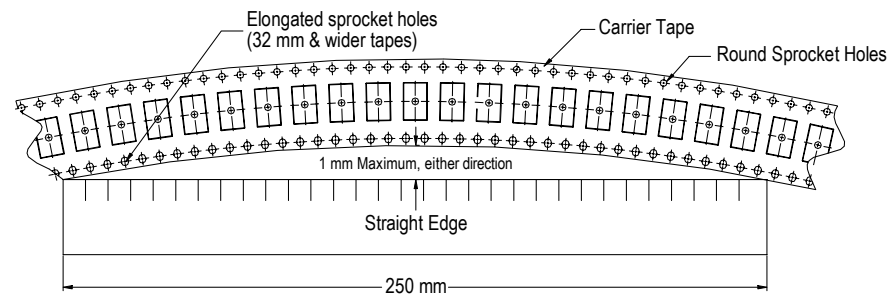
Metric will govern

Constant Dimensions — Millimeters (Inches)				
Tape Size	A	B Minimum	C	D Minimum
8 mm	178 ±0.20 (7.008 ±0.008) or 330 ±0.20 (13.000 ±0.008)	1.5 (0.059)	13.0 +0.5/-0.2 (0.521 +0.02/-0.008)	20.2 (0.795)
12 mm				
16 mm				
Variable Dimensions — Millimeters (Inches)				
Tape Size	N Minimum	W <sub>1</sub>	W <sub>2</sub> Maximum	W <sub>3</sub>
8 mm	50 (1.969)	8.4 +1.5/-0.0 (0.331 +0.059/-0.0)	14.4 (0.567)	Shall accommodate tape width without interference
12 mm		12.4 +2.0/-0.0 (0.488 +0.078/-0.0)	18.4 (0.724)	
16 mm		16.4 +2.0/-0.0 (0.646 +0.078/-0.0)	22.4 (0.882)	

**Figure 6 – Tape Leader & Trailer Dimensions**



**Figure 7 – Maximum Camber**



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**Central**  
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**West**  
Milpitas, CA  
Tel: 408-433-9950

**Mexico**  
Guadalajara, Jalisco  
Tel: 52-33-3123-2141

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**Southern Europe**  
Paris, France  
Tel: 33-1-4646-1006

Sasso Marconi, Italy  
Tel: 39-051-939111

**Central Europe**  
Landsberg, Germany  
Tel: 49-8191-3350800

Kamen, Germany  
Tel: 49-2307-438110

**Northern Europe**  
Bishop's Stortford, United Kingdom  
Tel: 44-1279-460122

Espoo, Finland  
Tel: 358-9-5406-5000

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**Northeast Asia**  
Hong Kong  
Tel: 852-2305-1168

Shenzhen, China  
Tel: 86-755-2518-1306

Beijing, China  
Tel: 86-10-5829-1711

Shanghai, China  
Tel: 86-21-6447-0707

Taipei, Taiwan  
Tel: 886-2-27528585

**Southeast Asia**  
Singapore  
Tel: 65-6586-1900

Penang, Malaysia  
Tel: 60-4-6430200

Bangalore, India  
Tel: 91-806-53-76817

*Note: KEMET reserves the right to modify minor details of internal and external construction at any time in the interest of product improvement. KEMET does not assume any responsibility for infringement that might result from the use of KEMET Capacitors in potential circuit designs. KEMET is a registered trademark of KEMET Electronics Corporation.*

## Other KEMET Resources

Tools	
Resource	Location
Configure A Part: CapEdge	<a href="http://capacitoredge.kemet.com">http://capacitoredge.kemet.com</a>
SPICE & FIT Software	<a href="http://www.kemet.com/spice">http://www.kemet.com/spice</a>
Search Our FAQs: KnowledgeEdge	<a href="http://www.kemet.com/keask">http://www.kemet.com/keask</a>
Electrolytic LifeCalculator	<a href="http://www.kemet.com:8080/elc">http://www.kemet.com:8080/elc</a>

Product Information	
Resource	Location
Products	<a href="http://www.kemet.com/products">http://www.kemet.com/products</a>
Technical Resources (Including Soldering Techniques)	<a href="http://www.kemet.com/technicalpapers">http://www.kemet.com/technicalpapers</a>
RoHS Statement	<a href="http://www.kemet.com/rohs">http://www.kemet.com/rohs</a>
Quality Documents	<a href="http://www.kemet.com/qualitydocuments">http://www.kemet.com/qualitydocuments</a>

Product Request	
Resource	Location
Sample Request	<a href="http://www.kemet.com/sample">http://www.kemet.com/sample</a>
Engineering Kit Request	<a href="http://www.kemet.com/kits">http://www.kemet.com/kits</a>

Contact	
Resource	Location
Website	<a href="http://www.kemet.com">www.kemet.com</a>
Contact Us	<a href="http://www.kemet.com/contact">http://www.kemet.com/contact</a>
Investor Relations	<a href="http://www.kemet.com/ir">http://www.kemet.com/ir</a>
Call Us	1-877-MyKEMET
Twitter	<a href="http://twitter.com/kemetcapacitors">http://twitter.com/kemetcapacitors</a>

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